

CHIPLINK N-Channel Enhancement Mode Power MOSFET

Description

The LX3400L combines advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltage as low as 2.5V. This device is suitable for use as a load switch or PWM applications.

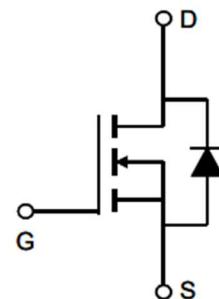
Features

- $V_{DS}=30V$, $I_D=5.1A$
- $R_{DS(ON)} < 33m\Omega$ @ $V_{DS}=10V$
- $R_{DS(ON)} < 39m\Omega$ @ $V_{DS}=4.5V$
- $R_{DS(ON)} < 55m\Omega$ @ $V_{DS}=2.5V$
- Low gate charge
- High power and current handling capability
- Termination is Lead-free and RoHS Compliant

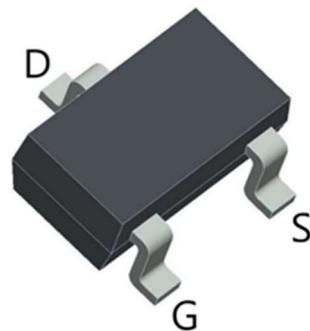


Applications

- PWM applications
- Load switch
- Power Management



schematic diagram



SOT23-3L Package

Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	5.1	A
Pulsed Drain Current ^B	I_{DM}	20	A
Maximum Power Dissipation ^A	P_D	1.3	W
Junction and Storage Temperature Range	T_J , T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction to Ambient	R_{QJA}	96	°C/W
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Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\text{\mu A}$	30			V
Gate-Threshold Voltage	$V_{\text{th(GS)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250 \text{\mu A}$	0.7	0.9	1.2	V
Gate-body Leakage	I_{GSS}	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 12\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$			1	uA
Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=5\text{A}$		24	33	mΩ
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4\text{A}$		26	39	mΩ
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=3\text{A}$		33	55	mΩ
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=5\text{A}$	10			s
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$		595		pF
Output Capacitance	C_{oss}			39		
Reverse Transfer Capacitance	C_{rss}			36		
Switching Capacitance						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=15\text{V}, R_{\text{L}}=3\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=3\Omega$		3.0		nS
Turn-on Rise Time	t_{r}			4.5		nS
Turn-off Delay Time	$t_{\text{d(off)}}$			25		nS
Turn-off Fall Time	t_{f}			3.8		nS
Total Gate Charge	Q_{g}	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=5\text{A}, V_{\text{GS}}=4.5\text{V}$		9.3		nC
Gate-Source Charge	Q_{gs}			1.6		nC
Gate-Drain Charge	Q_{gd}			2.1		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=5\text{A}$			1.2	V
Diode Forward Current	I_{s}				5.1	A

Notes:

- A. The Power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to ambient thermal resistance.
- B. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.
- C. The Static characteristics in Figures are obtained using $< 300 \mu\text{s}$ pulses, duty cycle 2% max.

Typical Electrical and Thermal Characteristics

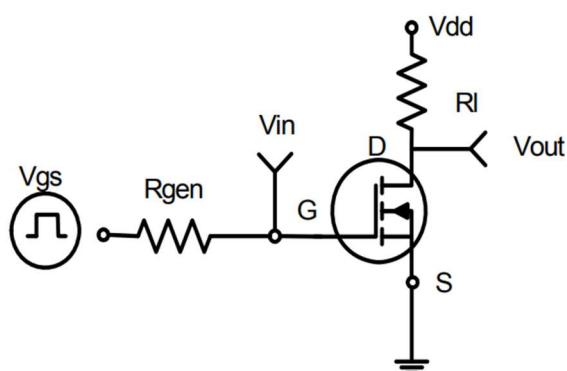


Figure 1:Switching Test Circuit

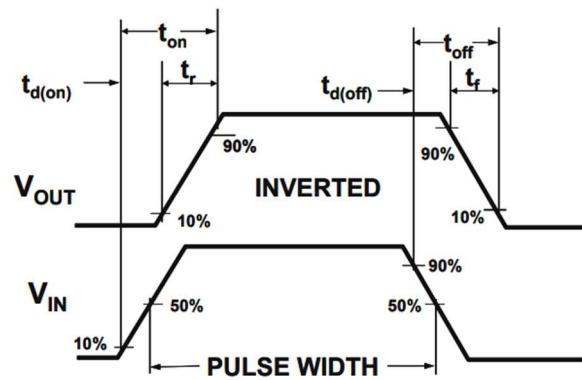


Figure 2:Switching Waveforms

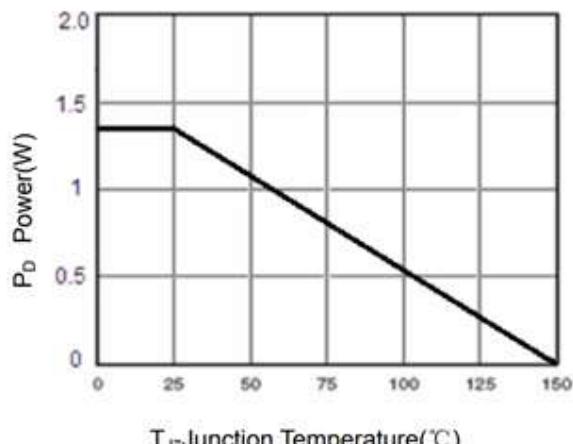


Figure 3 Power Dissipation

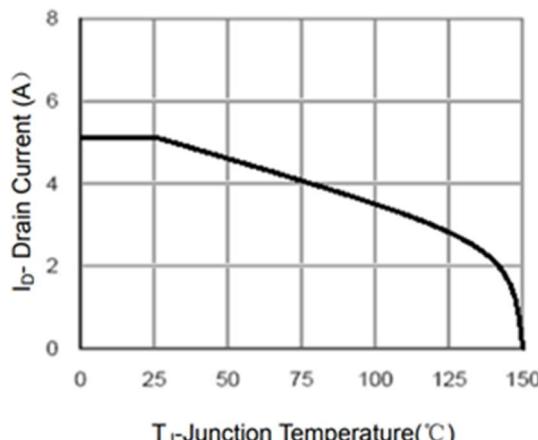


Figure 4 Drain Current

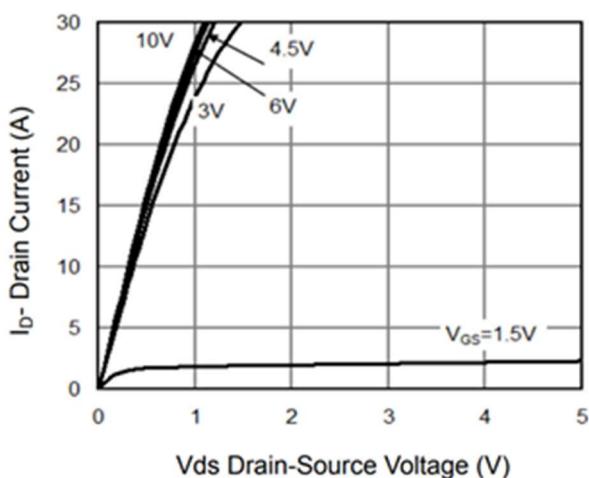


Figure 5 Output Characteristics

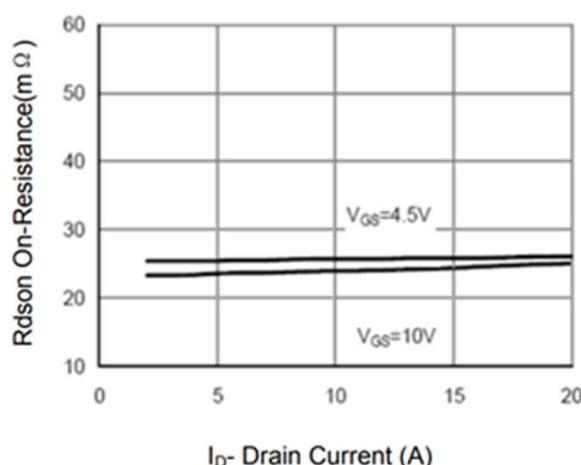


Figure 6 Drain-Source On-Resistance

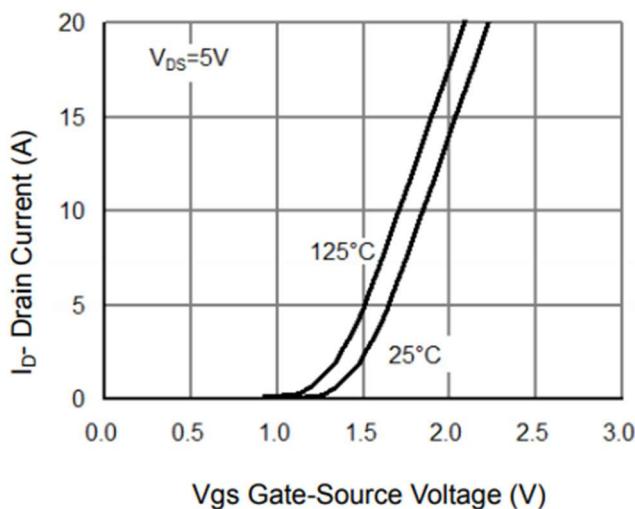


Figure 7 Transfer Characteristics

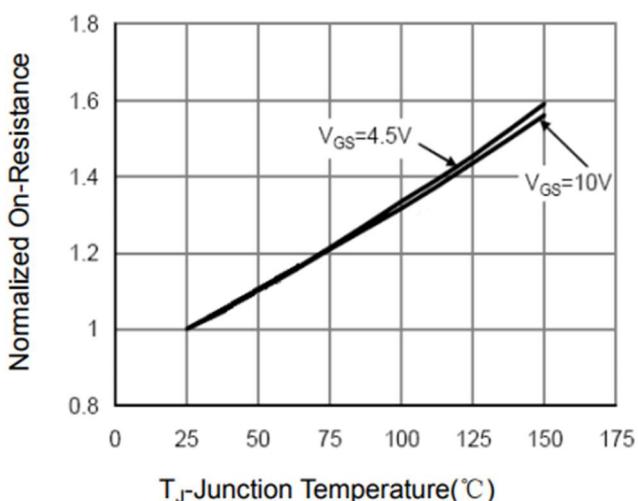


Figure 8 Drain-Source On-Resistance

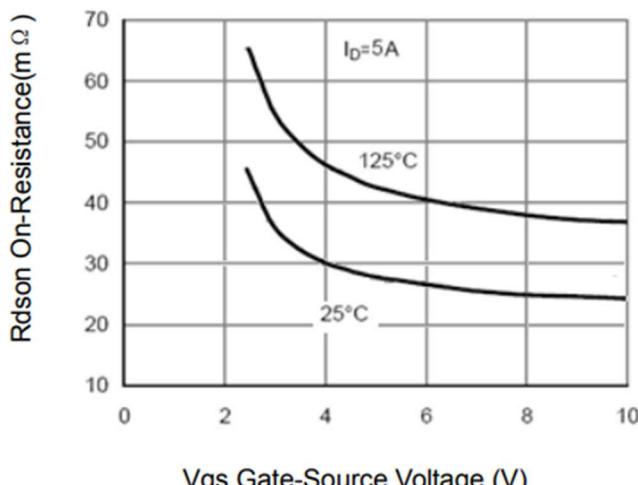


Figure 9 Rdson vs Vgs

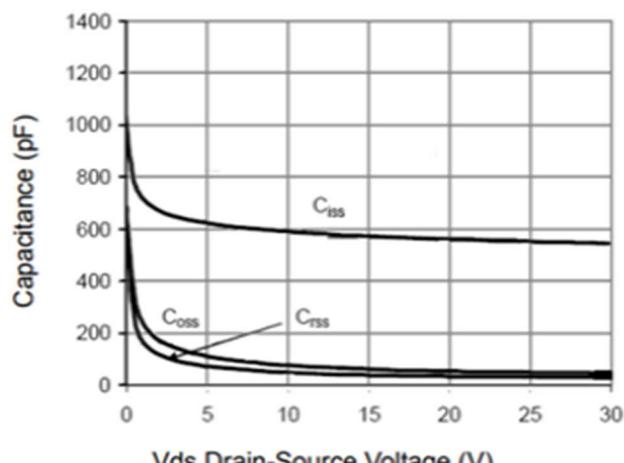


Figure 10 Capacitance vs Vds

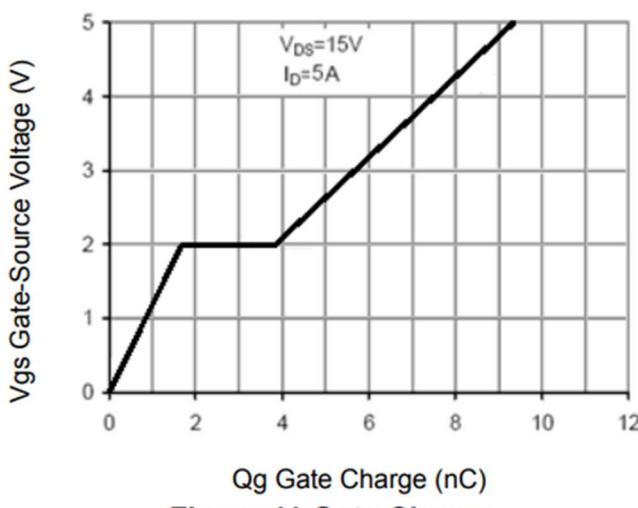


Figure 11 Gate Charge

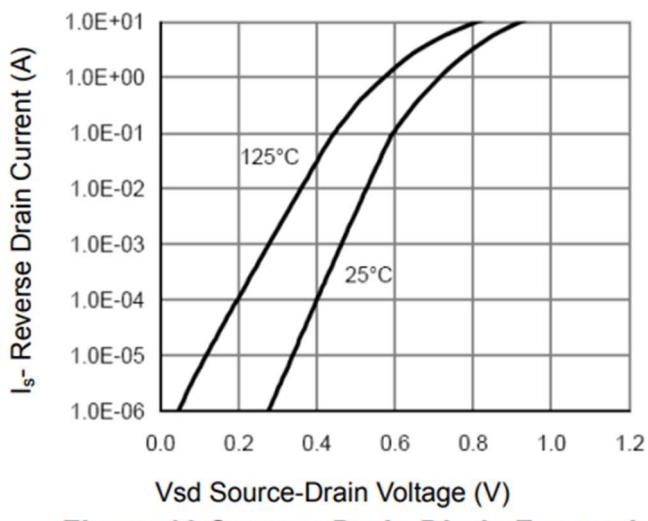


Figure 12 Source- Drain Diode Forward

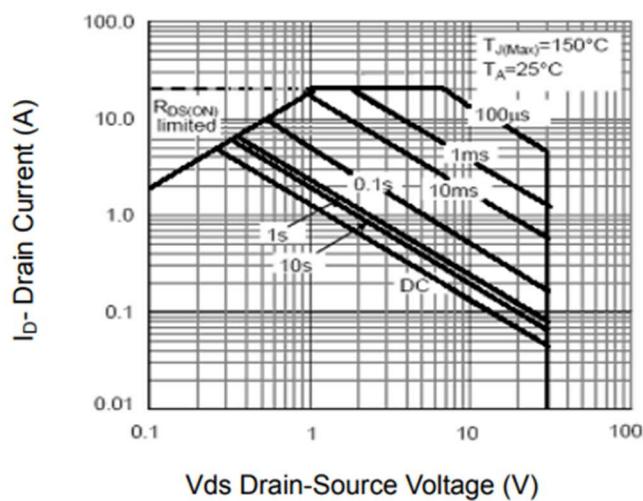


Figure 13 Safe Operation Area

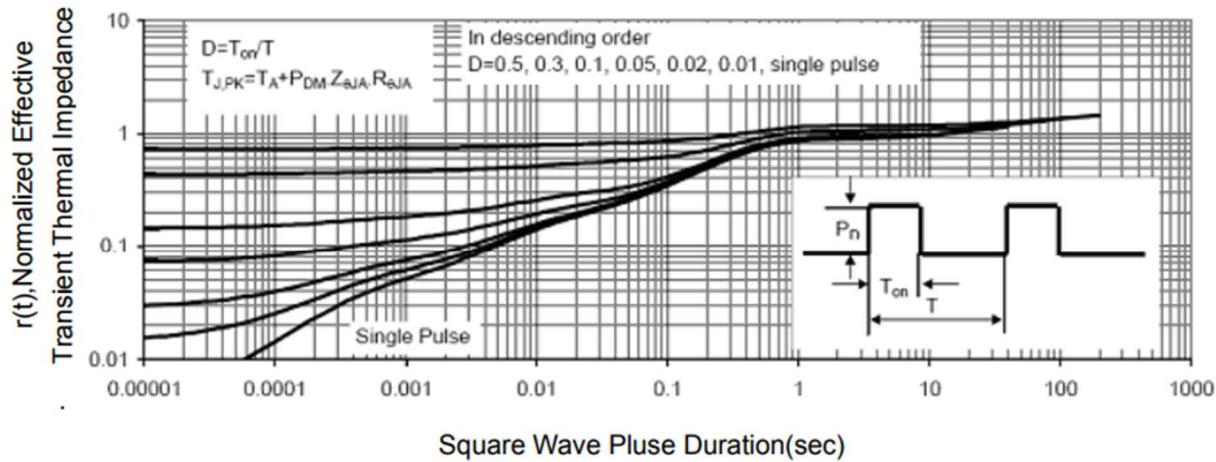
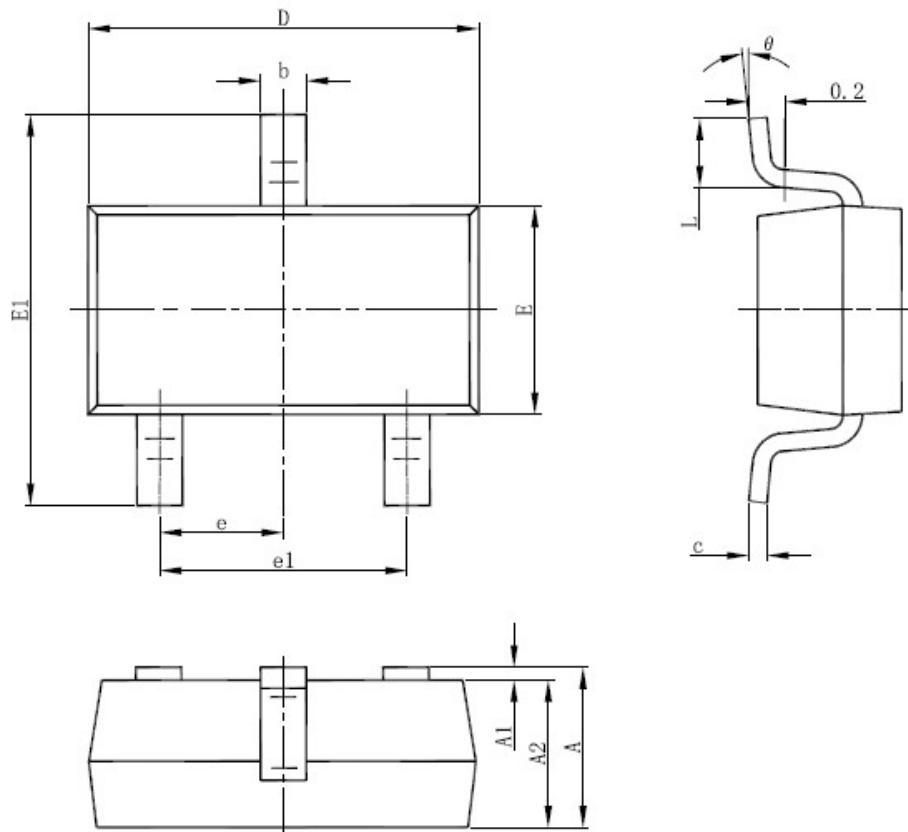


Figure 14 Normalized Maximum Transient Thermal Impedance

SOT23-3L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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